

ADVANCED INFORMATION

DESCRIPTION:

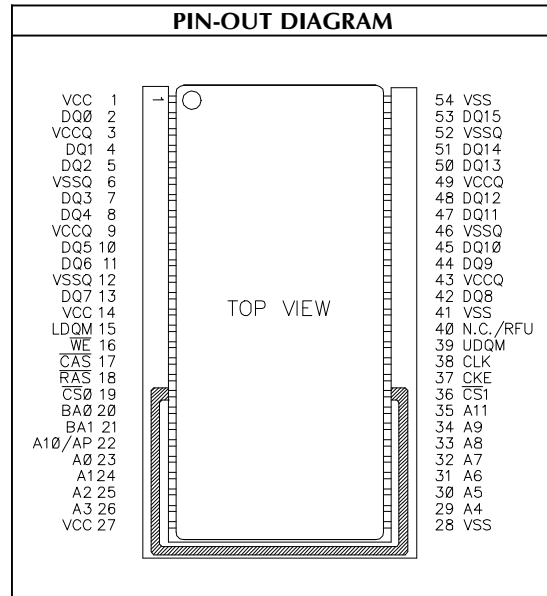
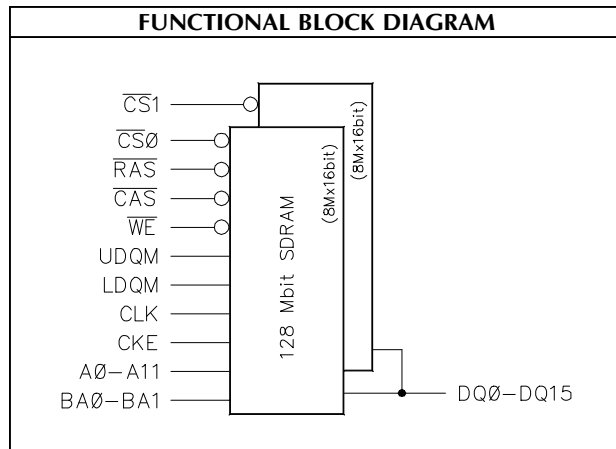
The *M-Densus* series is a family of interchangeable memory modules. The 256 Megabit SDRAM is a member of this family which utilizes the new and innovative space saving TSOP stacking technology. The modules are constructed with 8 Meg x 16 SDRAMs.

This 128 Megabit based *M-Densus* module, the DPSD16MX16TY5 has been designed to fit in the same footprint as the 8 Meg x 16 SDRAM TSOP monolithic and 128 Megabit SDRAM based family of *M-Densus* modules. This allows the memory board designer to upgrade the memory in their products without redesigning the memory board, thus saving time and money.

FEATURES:

- Configuration Available:
16 Meg x 16 bit (with two Chip Selects)
- Clock Frequency:
66^[1], 83^[1], 100, 125^[2], 133^[2] MHz (max.)
- PC100 and PC133 Compatible
- 3.3V Supply
- LVTTTL Compatible I/O
- Four Bank Operation
- Programmable Burst Type, Burst Length, and CAS Latency
- 4096 Cycles / 64 ms
- Auto and Self Refresh
- Package: TSOP Leadless Stack

NOTES: [1] Available in Industrial Temperature Ranges Only.
[2] Available in Commercial Temperature Range Only.



PIN NAMES	
A0 - A11	Row Address: A0 - A11 Column Address: A0 - A8
BA0, BA1	Bank Select Address
DQ0 - DQ15	Data In / Data Out
CAS	Column Address Strokes
RAS	Row Address Enables
WE	Data Write Enable
UDQM, LDQM	Upper & Lower Data Input/Output Mask
CKE	Clock Enable
CLK	System Clock
CS0-CS1	Chip Selects
Vcc/Vss	Power Supply/Ground
Vccq/Vssq	Data Output Power/Ground
N.C./RFU	No Connect Reserved for Future Use

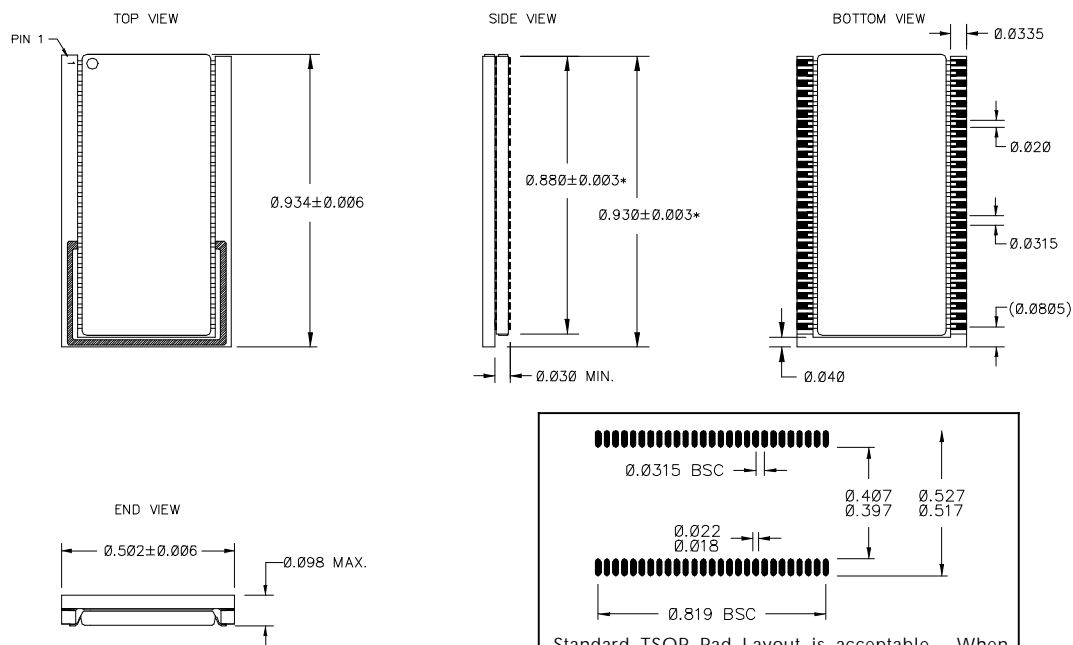
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PART NUMBER DESCRIPTION

DP	SD	16M	X	16	T	Y5	—	DP	—	XX	XX	X	X	
PREFIX	TYPE	MEMORY DEPTH	DESIG	MEMORY WIDTH	DESIG	PACKAGE	SUPPLIER	MEMORY	SPEED	CL	GRADE			
														Blank Commercial Temperature Industrial Temperature ^[4]
														2 CAS LATENCY 2
														15 ^[1] 15ns (66MHz) ^[1]
														12 ^[1] 12ns (83MHz) ^[1]
														10 10ns (100MHz)
														08 ^[2] 8ns (125MHz) ^[2]
														75 ^[2] 7.5ns (133MHz) ^[2]
														P1 PC100
														MANUFACTURER CODE ^[3]
														SUPPLIER CODE ^[3]
														STACKABLE TSOP
														128 MEGABIT LVTTL BASED
														MEMORY MODULE WITHOUT SUPPORT LOGIC
														SYNCHRONOUS DRAM

NOTES: [1] Available in Industrial Temperature Ranges Only. See Note 4.
 [2] Available in Commercial Temperature Range Only.
 [3] Contact your sales representative for supplier and manufacturer codes.
 [4] Delivery of all industrial temperature ranges are subject to availability of screened components.

MECHANICAL DRAWING



Standard TSOP Pad Layout is acceptable. When possible, use the Dense-Pac recommended footprint as shown. See Application Note 53A001-00 for further

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